Ten Reasons to Work with Intel Foundry

Semiconductor manufacturers need to optimize beyond traditional foundry models. Intel Foundry combines world-class process nodes, industry-leading packaging technologies, and a rich portfolio of semiconductor and systems IP. Here are a few reasons to work with Intel Foundry.

Now you can work with one semiconductor provider that meets the full

Power Delivery

Intel 3

Europe

Ireland

Cooling

A systems foundry approach

breadth of your needs. Intel Foundry is the world's first "systems foundry" — a full-stack approach that integrates chip and systems IP, process nodes, and advanced packaging and test, plus Systems Acceleration Services for architecture and design to help bring it all together. We can take you from initial specifications to finished devices and deliver it all at global scale.

Services

Acceleration

Services Soft IP SoC Sockets Advanced System Assembly & Test (ASAT) Advanced Chiplet Packaging FCBGA, EMIB, Foveros, Foveros Direct

Network

SW & Tools

System

Acceleration

Design Acceleration **Services**

Advanced Packaging & Test

Intel UMC 12

Intel 16

Advanced Chiplet Testing Advanced Technologies Die Sort & Prep, Test & Finish Substrates, Photonic Interconnect

World Class Foundry Offering

Design Ecosystem: Intel Foundry Accelerator

Americas

Process Nodes Intel 18A Intel 14A 1st w. High-NA EUV 1st w. PowerVia

Resilient, Sustainable. Secure Supply

Arizona Costa Rica New Mexico Ohio Oregon Santa Clara

Asia

We're flexible

Chengdu Israel Malaysia Vietnam

your entire project. Work with us at any point in your process: design with us, fab with us, or send us dies to package and test.

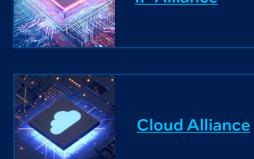
40+ ecosystem partners

Intel Foundry is open and flexible. Bring your own tooling, designers, and EDA partners. Mix and match our services with preferred vendors, or rely on us for

EDA Alliance IP Alliance



Design Services Alliance





United States Military Aerospace and Government (USMAG) Alliance

business needs

existing processes and capabilities.

Value Chain Alliance





Equipped and optimized for the AI era Our tooling, process nodes, and packaging technologies are optimized for

the industrial production of complex system-on-chip designs, including those designed to run AI workloads across the performance spectrum.

Design with any architecture or IP your

Our fabs are ready to produce ARM, RISC-V, x86, and custom ASICs.

We also partner with leading industry design firms to better support your

Intel 18A process technology is ready for design and scheduled for volume production in 2025. Intel 18A introduces major process advances that expand performance beyond traditional node scaling.

Build on leading process technologies

Intel 18A advances

3D RibbonFET gate-all-around (GAA) transistors

PowerVia backside power

FinFET designs.



New transistor architecture delivers faster switching speeds,

improved performance per watt, enhanced electrostatic

control, and greater efficiency compared to traditional

Moves power delivery to the backside of the die, reducing interconnect congestion, lowering IR drop, and improving power efficiency, enabling higher performance in advanced chips.

Intel's differentiated high-density metal-insulator-metal



capacitors, called Omni MIM, enable ultra-high-density on-die decoupling capacitance, significantly reducing inductive power droop and enhancing power stability —

crucial for modern workloads like AI.

deliver complex systems of chips that increase density and performance for

Omni MIM

Advanced chiplet packaging Intel Foundry is a leading producer of 2.5D packages with more than 100 2.5D products in volume production. Our advanced, 3D packaging techniques

Foveros 2.5D, 3D

and Foveros Direct 3D

Foveros increases interconnect

and I/O density, unlocking new

Temp-stable substrates

Assembled packages

with improved yields

Current generation board recipes optimize heat management. Next

design possibilities.



Thermal compression

Test process

Native bump-test

probing

bonding

Al accelerators.

generation glass substrates are Enables improved yields and reduces warpage. moving from lab to production. Rigorous testing, high yields

Advanced, multi-stage testing eliminates faulty dies early in the process,

Known good dies go

to assembly

ensuring only known good dies advance to packaging and testing.



Resilient, secure supply chain We maintain a robust, global pipeline for everything from raw silica to finished

We're committed to sustainable

components. We have fabs on three continents, and we're investing in

capacity around the world. We help lead and shape industry best practices in securing our supply chain through contributions to numerous organizations

Singulated die test

and sort

and initiatives.

semiconductor manufacturing We're committed and on track to reducing our environmental, energy, and waste footprints.



in 2024.2

water and enabled restoration of 2.9 billion gallons.4

approximately 10.5 billion gallons of

In 2024, Intel helped conserve

98% global renewable electricity

Intel reached 98% global renewable

electricity across global operations

Systems Accelerated

network of fabs and assembly and test sites.



66% of our manufacturing waste

is reused, recovered, or recycled³

of manufacturing waste in 2024.

Intel upcycled approximately 87,100 tons

in 2006 and have dropped 70% since.

expertise and advancing Moore's Law for the entire industry.

Intel Foundry: Al Inspired.

Let's talk

Intel Foundry is an independent, full-service semiconductor manufacturer headquartered in

the United States. We offer design, foundry, packaging, assembly, and test through a global

A long legacy of innovation

Intel commercialized the semiconductor 50 years ago, and we haven't

stopped innovating and scaling since. Now we're sharing all of our

intel.com/foundry

foundry.contact@intel.com

 $and\ software\ are\ intended\ only\ to\ be\ used\ in\ applications\ that\ do\ not\ cause\ or\ contribute\ to\ adverse\ impacts\ on\ human\ rights.$

Intel Foundry is open to fabless semiconductor designers, government

agencies, research labs, and academic programs. We appreciate any

opportunity to discuss your manufacturing, assembly, and test needs.

1. Subject to market conditions and incentives. Scale of some investments contingent on U.S. and EU support. These statements are based on current expectations and involve many and involve many are the support. These statements are based on current expectations and involve many are the support. These statements are based on current expectations and involve many are the support. The support is the support of the support orisks and uncertainties that could cause actual results to differ materially from those expressed or implied in such statements. For more information on the factors that could cause actual results to differ materially, see our most recent earnings release and SEC filings at www.intc.com

in Intel Foundry



No product or component can be absolutely secure.

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Sources:

5. Intel's 2024-25 Corporate Responsibility Report (CSR) Details regarding Intel's greenhouse gas emissions commitments and progress can be found beginning on page 36. Reference to research results, including comparisons to products, services or technology performance are estimates and do not imply availability. This material may contain information on products, services and technologies in development. Learn more at www.lntel.com/PerformanceIndex and <a ProcessInnovation.

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2. Intel's 2024-25 Corporate Responsibility Report (CSR) Details regarding Intel's energy conservation commitments and progress can be found beginning on page 37. 3. Intel's 2024-25 Corporate Responsibility Report (CSR) Details regarding Intel's waste and circular economy commitments and progress can be found beginning on page 39. 4. Intel's 2024-25 Corporate Responsibility Report (CSR) Details regarding Intel's water stewardship commitments and progress can be found beginning on page 38.